Worked Solutions May 2011 EEE 207 Assume that width of levels in cB and VB is small e.f. Eg i.e. all levels are identical  $n_V = no. of e in VB = P(E_V). N_{tot} = N_{tot}$   $| + exp[(E_V - E_F)/KT]$ ni = no. of e in CB = P(EvtEg). Ntot = Ntot 1 + exp[(Ev+Eg-EF)/KT] Now, Ntot = Ny+n; , so Ntot = Ntot 1+ exp[(Ev-EF)/KT] 1+ exp[(EV+Eg-Ep)/KT] rearranging this gives: exp[(2Ev-2Ef+Eg)/KT] = 1 2EV-2EF+Eg = 0 Er = Ev + Eg/2 =  $\frac{N_{\text{tot}}}{1 + \exp[(E_{V}+E_{g}-E_{V}-E_{g}/2)/\kappa T]} = \frac{N_{\text{tot}}}{1 + \exp(\frac{E_{g}}{2\kappa T})}$ = Ntor exp (-E9/2KT) as Eg>KT usually . In x exp(A/T) where A = -Eg

- i) What is ni?  $ni^2 = np = 10^{12} \times 4 \times 10^3 = 4 \times 10^{32}$ i.  $ni = 2 \times 10^{16} \text{ m}^3$
- ii) What is Na?  $n \ll n$  is semiconductor is p-type with  $Na Nd \gg n$ :  $p = Na Nd \implies Na = p + Nd = 4 \times 10^{20} + 6 \times 10^{20}$   $Na = 10^{21} \text{ m}^{-3}$
- ii)  $G = 3.25 \text{m}' = e(p \mu n + n \mu e) = ep \mu n \text{ as } p > n$   $-' \mu n = \frac{3.2}{1.6 \times 10^{19} \times 4 \times 10^{20}} = 0.05 \text{ m}^2 \text{ V}^{-1} \text{ S}^{-1}$
- (c) Semiconductor is p-type with  $4\times10^2$  m<sup>3</sup> holes and  $\pi$ i =  $2\times10^1$  m<sup>3</sup>

  When  $\pi$ i  $\approx$   $\pi$  Na-Hd, semiconductor will lose its extrinsic p-type characteristic.  $\pi$ i  $\propto$  exp $\left(\frac{-Eg}{2KT}\right)$ At RT:

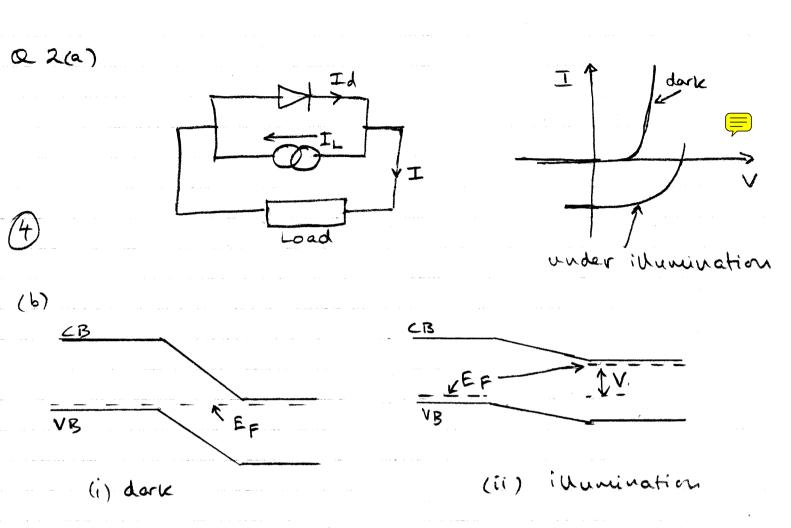
 $N_i = C \exp\left[\frac{-1.1 \times 1.6 \times 10^{-19}}{2 \times 1.38 \times 10^{-23} \times 293}\right] = 2 \times 10^{16} \text{ m}^3$ 

 $C \cdot \exp(-21.76) = C \cdot 3.53 \times 10^{-10} = 2 \times 10^{16}$  $C = 5.66 \times 10^{25} \text{ m}^3$ 

At Thit:  $n'_{i} = 4 \times 10^{20} = 5.66 \times 10^{25} \text{ exp} \left[ \frac{-1.1 \times 1.6 \times 10^{-19}}{2 \times 1.38 \times 10^{-23} \times T_{c}} \right]$ 7.06 ×  $10^{6} = \text{exp} \left[ -\frac{6376.8}{T_{c}} \right]$ 

-11.86 = -6376.8 x 1/T2 T2 = 537 k or 264°C

due to	change	in mobili	ing while	nge in cou still p-typues intrins	ee is
change At very	low T, carrier free	as p u	ouceutration	T there will in will not conviers w conductivi	change.



iii) Maximum voltage would be a band-gap of semiconductor

(c) Lougest wavelength is given by nanowest band-gap so \(\lambda\) max = 1.24/1.42 = 0.873 \(\mu\)m

Detectable wavelength of 820 nm = 1.512 eV Total band-gap = 1.42 + Eie + Eih = 1.512 eV

$$E_{1e} = \frac{(6.63 \times 10^{-34})^{2}}{8 \times 0.06 \times 9.11 \times 10^{31} \times 1.6 \times 10^{-19}} \cdot \frac{1}{L^{2}} = \frac{6.28 \times 10^{-18}}{L^{2}} \text{ L}^{2}$$

$$E_{1h} = \frac{(6.63 \times 10^{-34})^{2}}{8 \times 0.45 \times 9.11 \times 10^{-31} \times 1.6 \times 10^{19}} \cdot \frac{1}{L^{2}} = 8.37 \times 10^{19} \text{ eV}$$

Q2-C)

cont

$$\frac{1}{L^2} \left( 6.28 \times 10^{-18} + 8.37 \times 10^{-19} \right) = 0.092 \text{ eV}$$

$$L^{2} = \frac{7.12 \times 10^{-18}}{0.092} = 77.36 \times 10^{-18}$$

L = 8.8 x10 m = 8.8 nm





(d) As the well width reduces, the AlGats barrier becomes the limit, so  $\lambda_{max} = 1.24/1.8 = 0.69 \mu m$  The confined levels cannot be higher than the height of the barrier.



ohnic schottiky gate ohnic drain

n+ gate oxide n+ heavily doped

n+ region

Vs = 0, Vg = time, Vd = tive

At low Vg, holes repelled from under gate. At higher Vg, electrous form a conducting channel. Vds causes causes current to flow bedween source to drain

- (b) dId = MeCg [Vg-V7-Vd]
  - (i) to get Id, integrate above expression:

    Id = HeCg [Vg-VT-Vd] Vd
- (i) Saturation occurs when Id = maximum, i.e. when dId = 0, i. Vg-V-Vd = 0  $dV_d$

so Vd for saturation = Vg-VT

To get saturation current, Ids, substitutive  $Vd = Vg - V_T$ into expression for Id:  $Ids = \frac{|LeC_3|}{\ell^2} \frac{Vd^2}{2}$ 

Q36) transconductance, 
$$g_m = \frac{\partial I_d}{\partial V_g} |_{V_d}$$
, in saturation region (iii)

rearrange and substitute for Ids

$$\mu_{e} C_{g} = \frac{g_{m}}{Vd} = \frac{2 I ds}{Vd^{2}}$$

$$f_{i}, \qquad g_{i} = \frac{2 \text{ Ids}}{V_{d}}$$

(c) 
$$R_L = 5K\Omega$$
,  $Ids = 50mA$ ,  $gain = 25$   
 $gain = 9mR_L \implies 9m = 9ain/R_L = 5mS$ 

$$\frac{2 \text{ Ids}}{\text{Vd}} = \frac{9 \text{ ain}}{\text{RL}}$$
,  $\text{Vd} = \frac{2 \text{ Ids}}{\text{gain}} \text{RL}$ 

$$Vd = \frac{2 \times 50 \text{ mA} \times 5 \text{ kSR}}{25} = 20 \text{ V}$$

(4)  

$$Er = 11.8$$
,  $Cg = 0.2pF$ ,  $\mu = 0.13 \text{ m}^2 \text{ V} \cdot \text{S}^{-1} \cdot \text{I}$  (n-channel)  
 $gm = 5mS = \mu e Cg \text{ Vd}$ 

$$L^2 = \frac{0.13 \times 2 \times 10^{13} \times 20}{5 \times 10^{-3}}$$
  $L = 10 \mu m$ 

For gate,  $l/\omega = 0.5 \implies \omega = l \times 2 = 20 \mu M$ , to = 0xide thick  $C_9 = \underbrace{\epsilon_0 \epsilon_r \times l \times \omega} \implies l_0 = (\epsilon_0 \epsilon_r \times l \times \omega)/C_9$ 

$$Q_{4}(a)$$
 Force = rate of change in momentum  
=  $\frac{dp}{dt} = \frac{dk}{dt}$  as  $p = \frac{dk}{dt}$ 

Acceleration = 
$$\frac{d \left( \text{velocity} \right)}{dt} = \frac{1}{h} \frac{d^2 E}{dk^2} \cdot \frac{dk}{dt}$$
  
=  $\frac{1}{h^2} \cdot \frac{d^2 E}{dk^2} \cdot \text{Force}$ 

Force = mass x accleration, so rearranging above mass = 
$$m_e^* = t_1^2/(d^2E/dK^2)$$

$$\frac{dE}{dk} = 2Bk$$
 and  $\frac{d^2E}{dk^2} = 2B$ 

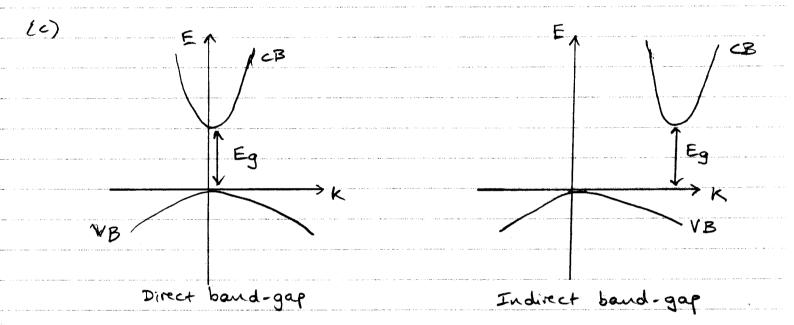
$$B = \frac{h^2}{2 \times 0.04 \times 9.11 \times 10^{-31}} = \frac{(6.626 \times 10^{-34} / 2 \text{ T})^2}{(2 \times 0.04 \times 9.11 \times 10^{-3})}$$

$$= 1.526 \times 10^{-37} \text{ Jm}^2 = 9.54 \times 10^{-19} \text{ eV m}^2$$

$$= 0.755 + 9.51 \times 10^{-19} \text{ V}^2 \text{ eV}$$

Q4(b) The E-K relationship becomes non-parabolic as we cont. more away from the zone centre and the effective mass increases.

(8)



Recombination in direct gap semiconductor occurs at K=0 and is an efficient process. Recombination in indirect gap semiconductor involves phonous, so is inefficient.

Lasers tweefore are made from direct gap semiconductors

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